

IN THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

D1 1. (currently amended) An ultrafine copper alloy wire with a diameter of not more than 0.08 mm, said ultrafine copper alloy wire being formed of a copper alloy wire consisting essentially of:

high-purity copper having a ~~total unavoidable impurity content of not more than 1 ppm~~ purity of 99.9999% or more by mass; and, added to the high-purity copper, 1.0 to 5.0% by mass of silver having a purity of not less than 99.99% by mass.

2. (currently amended) An ultrafine copper alloy wire with a diameter of not more than 0.08 mm, said ultrafine copper alloy wire being formed of a copper alloy wire consisting essentially of:

high-purity copper having a ~~total unavoidable impurity content of not more than 1 ppm~~ purity of 99.9999% or more by mass; and, added to the high-purity copper, 1.0 to 5.0% by mass of silver having a purity of not less than 99.99% by mass and 0.01 to 0.5% by mass of magnesium having a purity of not less than 99.9% by mass.

3. (currently amended) An ultrafine copper alloy wire with a diameter of not more than 0.08 mm, said ultrafine copper alloy wire being formed of a copper alloy wire consisting essentially of:

high-purity copper having a ~~total unavoidable impurity content of not more than 1 ppm~~ purity of 99.9999% or more by mass; and, added to the high-purity copper, 1.0 to 5.0% by mass of silver having a purity of not less than 99.99% by mass and 0.01 to 0.3% by mass of indium having a purity of not less than 99.99% by mass.

4. (previously amended) The ultrafine copper alloy wire according to claim 1, wherein said copper alloy wire has thereon a tin plating, a silver plating, a nickel plating, a tin-lead solder plating, a tin-silver plating, a tin-copper plating, a tin-silver-copper plating, or a tin-silver-copper-bismuth plating.

5-14. (canceled)

15. (previously presented) The ultrafine copper alloy wire according to claim 2, wherein said copper alloy wire has thereon a tin plating, a silver plating, a nickel plating, a tin-lead solder plating, a tin-silver plating, a tin-copper plating, a tin-silver-copper plating, or a tin-silver-copper- bismuth plating.

16. (previously presented) The ultrafine copper alloy wire according to claim 3, wherein said copper alloy wire has thereon a tin plating, a silver plating, a nickel plating, a tin-lead solder plating, a tin-silver plating, a tin-copper plating, a tin-silver-copper plating, or a tin-silver-copper- bismuth plating.

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17. (currently amended) A copper alloy wire having a diameter of not more than 0.08 mm, formed of elements consisting essentially of:

high-purity copper having a minimum 99.9999% purity; and

at least one of (i) 1.0% to 5.0% by mass of silver, and (ii) 0.01% to 0.5% by mass of magnesium or 0.01% to 0.3% by mass of indium metal combined with the high-purity copper.

18. (previously amended)) A copper alloy wire according to claim 17, wherein the at least one of (i) the silver, and (ii) the magnesium or the indium is the 1.0% to 5.0% by mass of silver and the silver has a purity of not less than 99.99% by mass.

19-20. (canceled)

21. (previously amended)) A copper alloy wire according to claim 17, wherein the at least one of (i) the silver, and (ii) the magnesium or the indium is the 1.0% to 5.0% by mass of silver and the silver has a purity of not less than 99.99% by mass, and the 0.01% to 0.5% by mass of magnesium and the magnesium has a purity of not less than 99.9% by mass.

22. (previously amended)) A copper alloy wire according to claim 17, wherein the at least one of (i) the silver, and (ii) the magnesium or the indium is the 1.0% to 5.0% by mass of silver and the silver has a purity of not less than 99.99% by mass, and the 0.01% to 0.3% by mass of indium and the indium has a purity of not less than 99.99% by mass.

23. (canceled)

24. (previously presented) A copper alloy wire according to claim 17, wherein the copper alloy wire is an ultrafine copper alloy wire.

25. (previously amended) A copper alloy wire according to claim 17, further comprising:

a plurality of other copper alloy wires;

wherein, the copper wire and the plurality of other copper wires form a stranded copper alloy wire conductor.

26. (previously presented) A copper alloy wire according to claim 25, wherein the stranded copper alloy wire conductor is one of an inner conductor and an outer conductor of an extrafine coaxial cable.

27. (previously amended) A copper alloy wire according to claim 26, wherein the stranded copper alloy wire conductor is the inner conductor of the extrafine coaxial cable, and further comprising:

a plurality of other copper alloy wire conductors;

wherein the plurality of other copper alloy wire conductors form outer conductors the extrafine coaxial cable.

28. (previously presented) The ultrafine copper alloy wire according to claim 1, wherein said copper alloy wire consists of:

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high-purity copper having a total unavoidable impurity content of not more than 1 ppm by mass; and

added to the high-purity copper, 1.0 to 5.0% by mass of silver having a purity of not less than 99.99% by mass.

29. (previously presented) The ultrafine copper alloy wire according to claim 2, wherein said copper alloy wire consists of:

high-purity copper having a total unavoidable impurity content of not more than 1 ppm by mass; and

added to the high-purity copper, 1.0 to 5.0% by mass of silver having a purity of not less than 99.99% by mass and 0.01 to 0.5% by mass of magnesium having a purity of not less than 99.9% by mass.

30. (previously presented) The ultrafine copper alloy wire according to claim 3, wherein said copper alloy wire consists of:

high-purity copper having a total unavoidable impurity content of not more than 1 ppm by mass; and

added to the high-purity copper, 1.0 to 5.0% by mass of silver having a purity of not less than 99.99% by mass and 0.01 to 0.3% by mass of indium having a purity of not less than 99.99% by mass.

31. (previously presented) The copper alloy wire according to claim 17, wherein the wire consists of:

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high-purity copper having a minimum 99.9999% purity; and
at least one of (i) 1.0% to 5.0% by mass of silver, and (ii) 0.01% to 0.5% by mass
of magnesium or 0.01% to 0.3% by mass of indium metal combined with the high-purity
copper.

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